

IN THE CLAIMS

Kindly cancel claims 1-34 without prejudice or disclaimer recited thereof:

Kindly add the following new claims:

35. A semiconductor device package manufacturing method comprising:
forming bumps on element electrodes of a semiconductor device by a wire bonding method;
positioning the semiconductor device on a thermoplastic resin sheet;
forming a thermoplastic resin portion for covering a portion of the semiconductor device except for end surfaces of the bumps by melting the thermoplastic resin sheet through hot pressing of the thermoplastic resin sheet and the semiconductor device; and
cutting the thermoplastic resin portion after the hot pressing.
36. A semiconductor device package manufacturing method comprising:
forming by a wire bonding method a bump on an element electrode of a semiconductor device of an individual piece obtained by dicing a semiconductor wafer;
positioning one or a plurality of the semiconductor devices on a thermoplastic resin sheet;
forming a thermoplastic resin portion for covering a portion of the semiconductor device except for an end surface of the bump by melting the thermoplastic resin sheet through hot pressing of the thermoplastic resin sheet and each individual piece of the semiconductor device; and
cutting the thermoplastic resin portion after the hot pressing.
37. A semiconductor device package manufacturing method comprising:

forming bumps on semiconductor device electrodes of a semiconductor wafer by a wire bonding method;

dicing the semiconductor wafer on which the bump is formed to divide the wafer into each individual piece of a semiconductor device;

positioning one or a plurality of the semiconductor devices on a thermoplastic resin sheet;

forming a thermoplastic resin portion for covering a portion of the semiconductor device except for end surfaces of the bumps by melting the thermoplastic resin sheet through hot pressing of the thermoplastic resin sheet and each individual piece of the semiconductor device; and

cutting the thermoplastic resin portion after the hot pressing.

38. A semiconductor device package manufacturing method comprising:

forming bumps on element electrodes of a semiconductor wafer by a wire bonding method;

positioning a thermoplastic resin sheet on the semiconductor wafer;

forming a thermoplastic resin portion for covering a portion of the semiconductor device except for end surfaces of the bumps by melting the thermoplastic resin sheet through hot pressing of the semiconductor wafer and the thermoplastic resin sheet; and

dicing the semiconductor wafer and the thermoplastic resin portion, which have undergone the hot pressing.

39. A semiconductor device package manufacturing method comprising:

printing a circuit pattern with a conductive paste in a thermoplastic resin portion that is located on an end surface side where the bump is exposed and belongs to a semiconductor device package manufactured by the semiconductor device package manufacturing method claim d in claim 35;

hardening the conductive paste with a metallic particle arranged in a specified position of the circuit pattern;

forming a thermoplastic resin portion for covering a portion of the semiconductor device except for an end surface of the metallic particle by positioning the semiconductor device package obtained after the hardening of the conductive paste on the thermoplastic resin sheet and melting the thermoplastic resin sheet through hot pressing; and

cutting the thermoplastic resin portion after the hot pressing.

40. A semiconductor device package manufacturing method comprising:

printing a circuit pattern with a conductive paste on an electrode surface side of a semiconductor device package manufactured by the semiconductor device package manufacturing method **claimed in claim 39**;

hardening the conductive paste with a metallic particle arranged in a specified position of the circuit pattern;

forming a thermoplastic resin portion for covering a portion of the semiconductor device except for an end surface of the metallic particle by positioning the semiconductor device package obtained after the hardening of the conductive paste on the thermoplastic resin sheet and melting the thermoplastic resin sheet through hot pressing; and

repeating cutting of the thermoplastic resin portion after the hot pressing in specified times, thereby forming a multi-layer package.

41. A semiconductor device package manufacturing method comprising:

printing a circuit pattern with a conductive paste on an electrode surface side of the semiconductor wafer before the dicing of the semiconductor wafer and the thermoplastic resin portion, which have undergone the hot pressing, according to the semiconductor device package manufacturing method of **claim 38**;

hardening the conductive paste with a metallic particle arranged in a specified position of the circuit pattern

forming a thermoplastic resin portion for covering a portion of the semiconductor device except for an end surface of the metallic particle by aligning in position the semiconductor wafer obtained after the hardening of the conductive paste with the thermoplastic resin sheet and melting the thermoplastic resin sheet through hot pressing; and

dicing the semiconductor wafer that has the metallic particle and has undergone the hot pressing;

42. A semiconductor device package manufacturing method comprising:

printing a circuit pattern with a conductive paste on an electrode surface side of the semiconductor wafer before the dicing of the semiconductor wafer and the thermoplastic resin portion, which have undergone the hot pressing, according to the semiconductor device package manufacturing method of **claim 38**;

hardening the conductive paste with a metallic particle arranged in a specified position of the circuit pattern; and

obtaining a multi-layer structure by repeating in specified times process of forming a thermoplastic resin portion for covering a portion of the semiconductor device except for an end surface of the metallic particle by aligning in position the semiconductor wafer obtained after the hardening of the conductive paste with the thermoplastic resin sheet and melting the thermoplastic resin sheet through hot pressing, and thereafter dicing the semiconductor wafer that has the metallic particle and has undergone the hot pressing.

43. A semiconductor device package manufacturing method as **claimed in claim 35**, wherein when the thermoplastic resin portion is formed, the thermoplastic resin sheet is melted and thereby covering the surface of the semiconductor device on which the bump is formed except for the end surface of the semiconductor device.

44. An electronic component module manufacturing method comprising:
printing a circuit pattern with a conductive paste on a first thermoplastic resin sheet;

mounting a semiconductor device package manufactured by the semiconductor device package manufacturing method **claimed in claim 35**, and an electronic component at specified positions of the circuit pattern of the first thermoplastic resin sheet; and

forming a thermoplastic resin portion for covering the semiconductor package and the electronic component by aligning in position a second thermoplastic resin sheet with the first thermoplastic resin sheet on which the semiconductor device package and the electronic component are mounted and melting the second thermoplastic resin sheet through hot pressing.

45. An electronic component module manufacturing method as **claimed in claim 44**, wherein when the thermoplastic resin portion is formed, a surface of the semiconductor device on which the bump is formed except for the end surface of the bump of the semiconductor device by melting the thermoplastic resin sheet.

46. A method for manufacturing a noncontact IC card having an antenna coil for executing transmission and reception between an IC chip and outside, the method comprising:

printing a circuit pattern capable of being electrically connected to an IC electrode portion of the IC chip or a circuit pattern to be electrically connected to the IC electrode portion including a coil pattern that constitutes the antenna coil on a thermoplastic resin base material with a conductive paste ;

arranging a semiconductor device package on the circuit pattern in a manner that the IC electrode portion of the IC chip of the semiconductor device package that has

the IC chip and is manufactured by the semiconductor device package manufacturing method **claimed in claim 35**, is connected to the circuit pattern;

hardening the conductive paste;

forming a thermoplastic resin portion for covering the semiconductor device package by aligning in position a thermoplastic resin sheet on a semiconductor device package mounting surface side of the thermoplastic resin base material obtained after the hardening of the conductive paste and melting the thermoplastic resin sheet through hot pressing; and

cutting the thermoplastic resin portion after the hot pressing, forming the card.

47. A semiconductor device package manufactured by the semiconductor device package manufacturing method **claimed in claim 35**.

48. A semiconductor device package manufactured by the semiconductor device package manufacturing method **claimed in claim 43**.

49. A semiconductor device-mounted component manufacturing method for performing mounting of a semiconductor device on a circuit pattern, which is electrically connected to the semiconductor device while being brought in contact with a bump of the semiconductor device and is formed of a conductive paste on a pattern forming surface of a base material, the method comprising:

inserting the semiconductor device into the base material with the bump of the semiconductor device put in an exposed state proximately to the pattern forming surface; and

forming a contact area increasing portion for increasing a contact area of the circuit pattern with the bump on the bump exposed on the pattern forming surface.

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50. A semiconductor device-mounted component manufacturing method as **claimed in claim 49**, wherein

the contact area increasing portion is formed of an extension portion-forming member brought in contact with the bump or the pattern forming surface located in a vicinity of the bump when the contact area is increased, and

the extension portion-forming member is pressurized against the bump or the pattern forming surface located in the vicinity of the bump.

51. A semiconductor device-mounted component manufacturing method as **claimed in claim 50**, wherein, when the extension portion-forming member has a cylindrical shape, a projecting portion is formed as the contact area increasing portion on the bump formed by a pressurizing operation for performing pressurization with the extension portion-forming member.

52. A semiconductor device-mounted component manufacturing method as **claimed in claim 50**, wherein, when the extension portion-forming member has a rugged portion at its tip, a rugged portion is formed as the contact area increasing portion on the bump formed by a pressurizing operation for performing pressurization with the extension portion-forming member.

53. A semiconductor device-mounted component manufacturing method as **claimed in claim 50**, wherein, when the extension portion-forming member has a cylindrical shape, a contact area increasing groove is formed in the vicinity of the bump by pressurizing the pattern forming surface in the vicinity of the bump by a pressurizing operation for performing pressurization with the extension portion-forming member, thus exposing the bump from the base material.

54. A semiconductor device-mounted finished-product manufacturing method for encapsulating **a** semiconductor device-mounted component manufactured by the semiconductor device-mounted component manufacturing method **claimed in claim 49**.

55. A semiconductor device-mounted finished-product provided with a semiconductor device-mounted component manufactured by the semiconductor device-mounted component manufacturing method **claimed in claim 49**.

56. A semiconductor device-mounted finished-product manufactured by the semiconductor device-mounted finished-product manufacturing method **claimed in claim 54**.

57. A semiconductor device-mounted finished-product as **claimed in claim 55**, wherein the semiconductor device-mounted finished-product is a noncontact IC card.

58. A semiconductor device-mounted finished-product as **claimed in claim 56**, wherein the semiconductor device-mounted finished-product is a noncontact IC card.

59. A semiconductor device-mounted component manufacturing apparatus for performing mounting of a semiconductor device on a circuit pattern, which is electrically connected to the semiconductor device while being brought in contact with a bump of the semiconductor device and is formed of a conductive paste on a pattern forming surface of a base material, the apparatus comprising:

a semiconductor device pressurizing device for inserting the semiconductor device into the base material with the bump of the semiconductor device put in an exposed state or an unexposed state proximately to the pattern forming surface; and

a contact area increasing device for forming a contact area increasing portion for increasing a contact area of the circuit pattern with the bump on the bump exposed or located proximately to the pattern forming surface.

60. A semiconductor device-mounted component manufacturing apparatus as **claimed in claim 59**, wherein

the contact area increasing device comprises:

an extension portion-forming member for forming the contact area increasing portion by coming in contact with the bump or in contact with the pattern forming surface located in the vicinity of the bump; and

an extension portion-forming member-use pressurizing device for pressurizing the extension portion-forming member against the bump or the pattern forming surface located in the vicinity of the bump.

61. A semiconductor device-mounted component manufacturing apparatus as **claimed in claim 60**, wherein

the extension portion-forming member has a cylindrical shape and forms a projecting portion that serves as the contact area increasing portion on the bump formed by a pressurizing operation for performing pressurization with the extension portion-forming member-use pressurizing device.

62. A semiconductor device-mounted component manufacturing apparatus as **claimed in claim 60**, wherein the extension portion-forming member has at its tip a rugged portion and forms a rugged portion as the contact area increasing portion on the bump formed by a pressurizing operation for performing pressurization with the extension portion-forming member-use pressurizing device.

63. A semiconductor device-mounted component manufacturing apparatus as **claimed in claim 60**, wherein the extension portion-forming member has a cylindrical shape and forms a contact area increasing groove in the vicinity of the bump by pressurizing the pattern forming surface located in the vicinity of the bump by a pressurizing operation for performing pressurization with the extension portion-forming member-use pressurizing device, thus exposing the bump from the base material.

64. A semiconductor device-mounted finished-product manufacturing apparatus comprising:

the semiconductor device-mounted component manufacturing apparatus **claimed in claim 59**; and

an encapsulating device for encapsulating the semiconductor device-mounted component manufactured by the semiconductor device-mounted component manufacturing apparatus.

65. A semiconductor device-mounted finished-product comprising the semiconductor device-mounted component manufactured by the semiconductor device-mounted component manufacturing apparatus **claimed in claim 59**.

66. A semiconductor device-mounted finished-product manufactured by the semiconductor device-mounted finished-product manufacturing apparatus **claimed in claim 64**.

67. A semiconductor device-mounted finished-product **claimed in claim 65**, wherein the semiconductor device-mounted finished-product is a noncontact IC card.

68. A semiconductor device-mounted finished-product **claimed in claim 66**, wherein the semiconductor device-mounted finished-product is a noncontact IC card.

69. A semiconductor device package manufacturing method comprising:
printing a circuit pattern with a conductive paste in a thermoplastic resin portion that is located on an end surface side where the bump is exposed and belongs to a semiconductor device package manufactured by the semiconductor device package manufacturing method **claimed in claim 36**;

hardening the conductive paste with a metallic particle arranged in a specified position of the circuit pattern;

forming a thermoplastic resin portion for covering a portion of the semiconductor device except for an end surface of the metallic particle by positioning the semiconductor device package obtained after the hardening of the conductive paste on the thermoplastic resin sheet and melting the thermoplastic resin sheet through hot pressing; and

cutting the thermoplastic resin portion after the hot pressing.

70. A semiconductor device package manufacturing method comprising:
printing a circuit pattern with a conductive paste in a thermoplastic resin portion that is located on an end surface side where the bump is exposed and belongs to a semiconductor device package manufactured by the semiconductor device package manufacturing method **claimed in claim 37**;

hardening the conductive paste with a metallic particle arranged in a specified position of the circuit pattern;

forming a thermoplastic resin portion for covering a portion of the semiconductor device except for an end surface of the metallic particle by positioning the semiconductor device package obtained after the hardening of the conductive paste on the thermoplastic resin sheet and melting the thermoplastic resin sheet through hot pressing; and

cutting the thermoplastic resin portion after the hot pressing.

71. A semiconductor device package manufacturing method as **claim d in claim 36**, wherein when the thermoplastic resin portion is formed, the thermoplastic resin sheet is melted and thereby covering the surface of the semiconductor device on which the bump is formed except for the end surface of the semiconductor device.

72. A semiconductor device package manufacturing method as **claimed in claim 37**, wherein when the thermoplastic resin portion is formed, the thermoplastic resin sheet is melted and thereby covering the surface of the semiconductor device on which the bump is formed except for the end surface of the semiconductor device.

73. A semiconductor device package manufacturing method as **claimed in claim 38**, wherein when the thermoplastic resin portion is formed, the thermoplastic resin sheet is melted and thereby covering the surface of the semiconductor device on which the bump is formed except for the end surface of the semiconductor device.

74. A semiconductor device package manufacturing method as **claimed in claim 40**, wherein when the thermoplastic resin portion is formed, the thermoplastic resin sheet is melted and thereby covering the surface of the semiconductor device on which the bump is formed except for the end surface of the semiconductor device.

75. A semiconductor device package manufacturing method as **claimed in claim 41**, wherein when the thermoplastic resin portion is formed, the thermoplastic resin sheet is melted and thereby covering the surface of the semiconductor device on which the bump is formed except for the end surface of the semiconductor device.

76. A semiconductor device package manufacturing method as **claimed in claim 42**, wherein when the thermoplastic resin portion is formed, the thermoplastic resin sheet

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is melted and thereby covering the surface of the semiconductor device on which the bump is formed except for the end surface of the semiconductor device.

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